

A detailed photograph of a microchip assembly process. A small, square, black microchip is mounted on a circular gold-colored substrate. This substrate is being held by a pair of gold-colored tweezers. Below it, a larger, cylindrical metal component with a flange and a central hole is visible. The background is a blue surface with some mechanical parts.

Advanced IR Sensors for Passive and Active Imaging Applications

AIM Infrarot-Module GmbH

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EPIC Online Technology Meeting on Photonics for
Defense – Active and Passive Imaging Systems

October 27th, 2025



EMPLOYEES

~410

REVENUE

~91 Mio. €

OWNER

50% Diehl
50% Rheinmetall

LOCATION

Germany

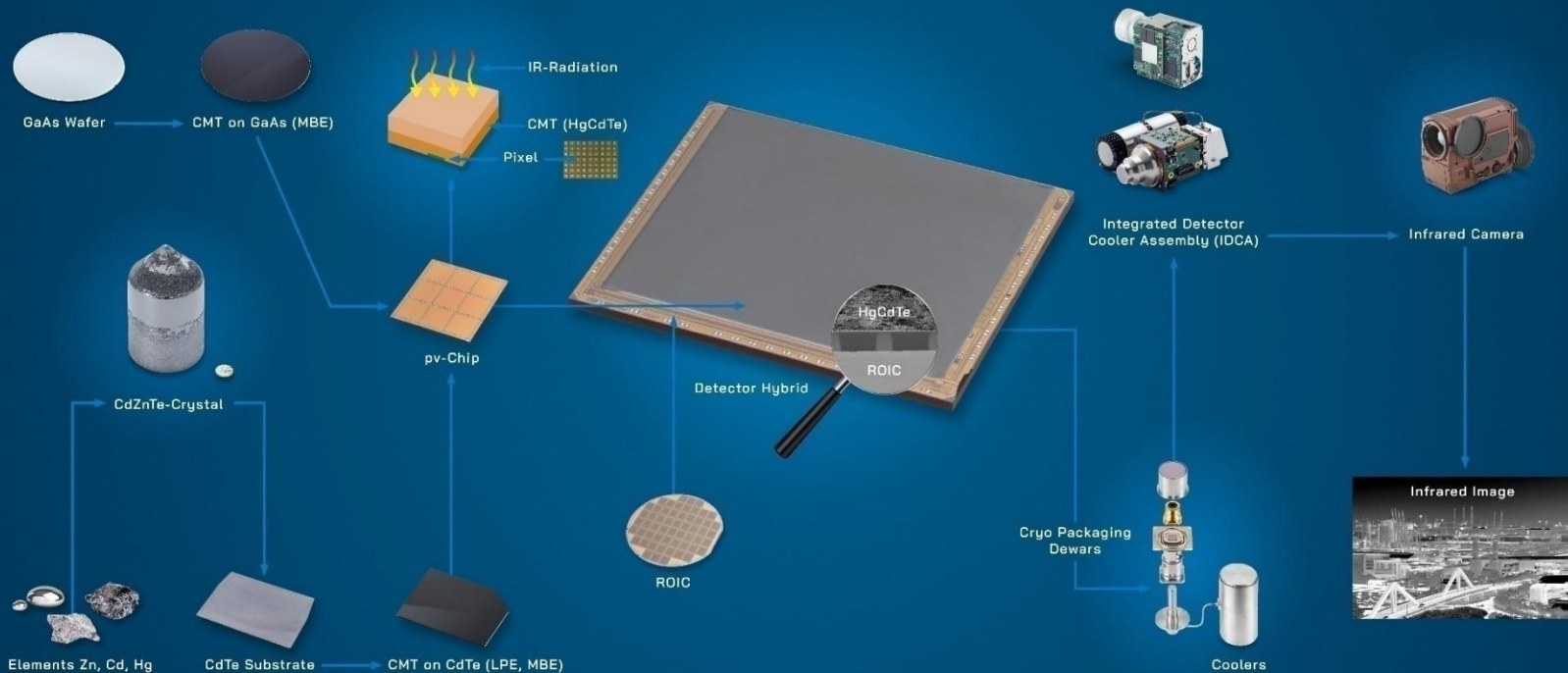
FACILITY

2.000sqm
clean room



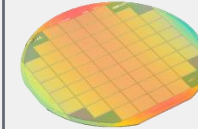
National Key Technology
Made in Germany

ALL RELEVANT TECHNOLOGIES FOR IR-DETECTORS UNDER ONE ROOF



- Coverage of the whole IR spectral range ($\text{Hg}_{1-x}\text{Cd}_x\text{Te}$): SWIR to VLWIR
- High resolution, low SWaP due small pixel pitch and HOT technology
- Dual-Color and Dual-Band technology

Detectors



Dewars



Cryo-coolers



Electronics



Integration



Test



VIS



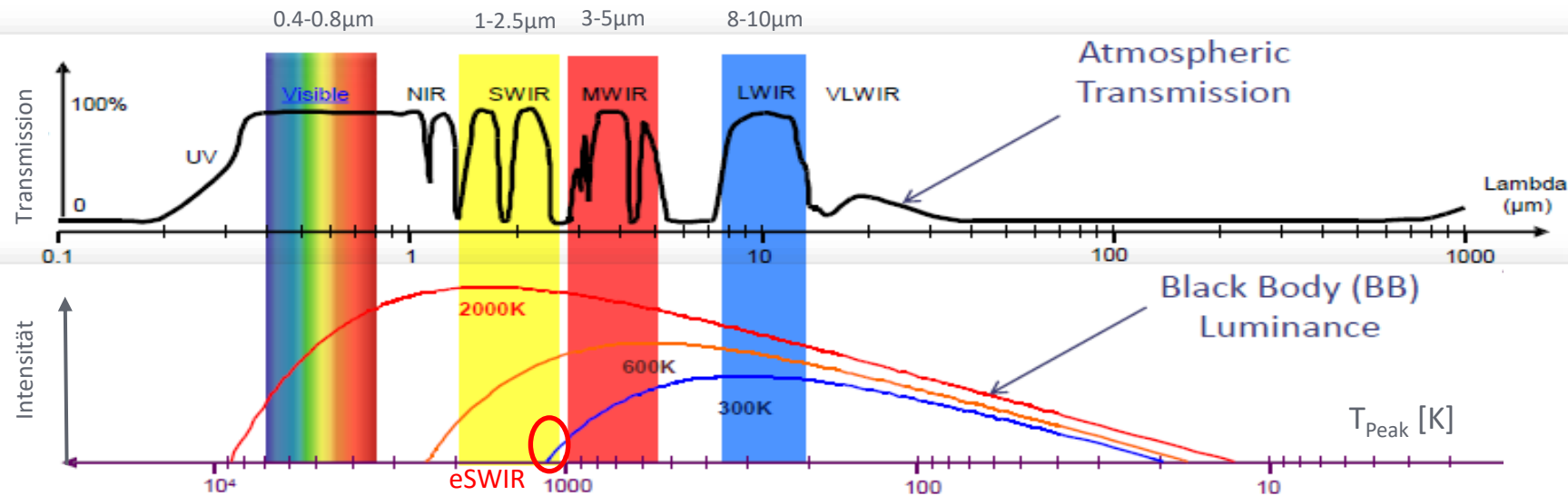
eSWIR



MWIR



LWIR



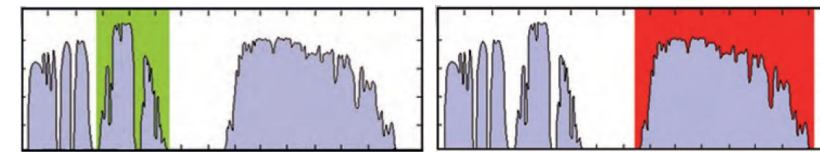
Source: TEMATYS SARL

Different conditions & tasks:

- **Condition:** Day, night, sunshine, fog, haze, rain, snow, turbulence, ...
- **Object:** Tanks, vehicles, UAVs, missiles, persons
- **Task:** Detection, recognition, identification

Advanced IR Sensors

MWIR or LWIR, high resolution and low SWaP



AIM

LPE MCT on CdTe

MWIR (3.4 μm – 5.0 μm)

Top 120K (p-on-n)

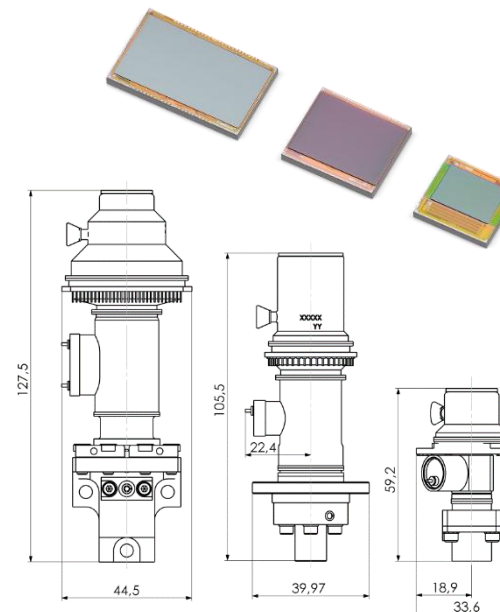
HOT MWIR (3.4 μm – 4.8 μm)

Top 160K (p-on-n)

LWIR (7.6 μm – 9.0 μm)

Top 100K (p-on-n)

- Small pixel pitch for higher resolution
- HOT technology for low Size, Weight and Power (SWaP)



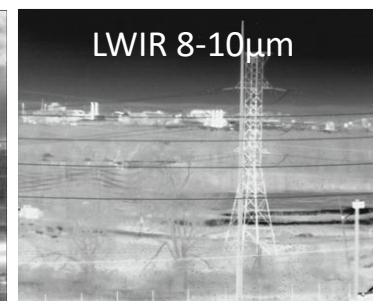
- ❑ **1280 x 720** / 12 μm pixel pitch
 - CHC ~7 Mio e^-
 - Framerate up to 75 Hz
- ❑ **1024 x 768** / 10 μm pixel pitch
 - CHC ~7 Mio e^-
 - Framerate up to 120 Hz
- ❑ **1280 x 1024** / 7.5 μm pixel pitch
 - CHC ~2.1 Mio e^-
 - Framerate up to 60 Hz
- ❑ **HOT MWIR**
 - **1280 x 1024** / 7.5 μm pixel pitch
 - **1024 x 768** / 10 μm pixel pitch
 - **640 x 512** / 10 μm pixel pitch
 - Framerate up to 60 Hz



MWIR 3-5 μm , $t_{\text{int}} > 1\text{ms}$

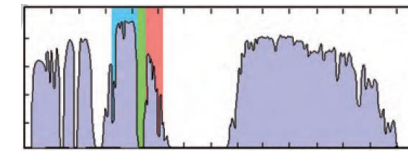


LWIR 8-10 μm , $t_{\text{int}} \sim 0.2\text{ms}$



~ 1.2 kg / 15W

~ 0.4 kg / 4W



MBE MCT on GaAs

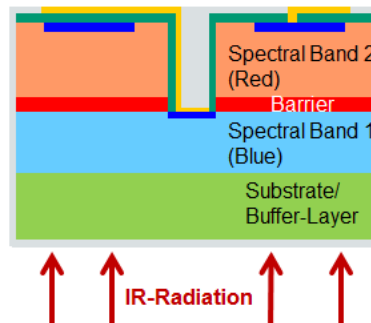
320x256 pixels, 30 μm pitch

■ Spatial coincidence:

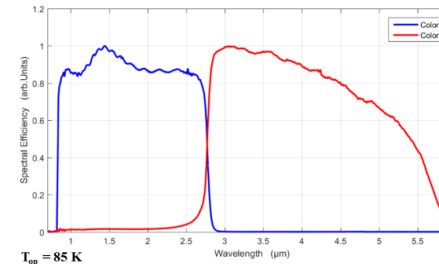
- Symmetrical and concentric areas for „blue“ and „red“ channels

■ Temporal coincidence:

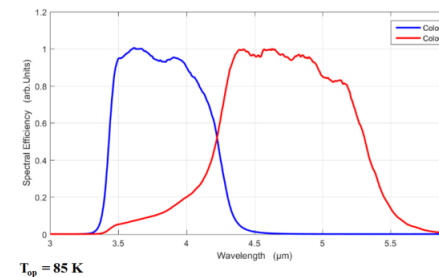
- 2 contacts per pixel for „blue“ and „red“ channels (plus one common mass contact)
- MCT n-on-p array technology



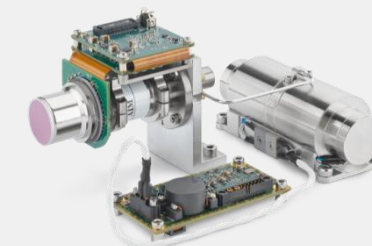
SW/MW



MW/MW

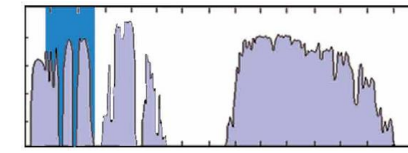


- Format **320x256**
- Pixel pitch 30 μm
- ROIC
 - DI input stage
 - CHC low gain 18 Mio e⁻ / 6.5 Mio e⁻ (R/B)
 - CHC high gain 5 Mio e⁻ / 1.5 Mio e⁻ (R/B)
 - Clock 12 MHz
 - Snapshot, Integrate Then Read (ITR)
 - Modes: Signal Color, Dual Color, HDR
 - Framerate up to ~500 Hz
 - 8 Outputs (4 Red + 4 Blue)



Advanced IR Sensors

eSWIR Imaging, $\lambda_{co} = 2.5\mu\text{m}$



AIM

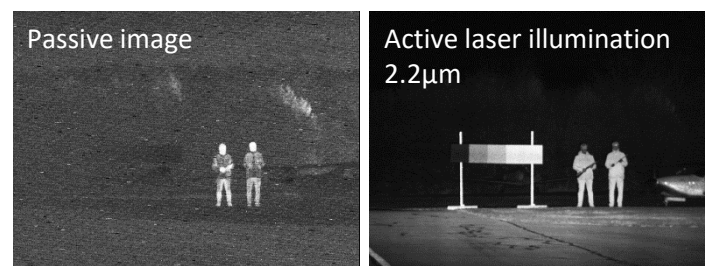
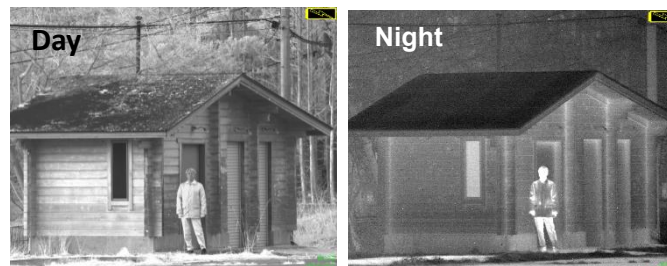
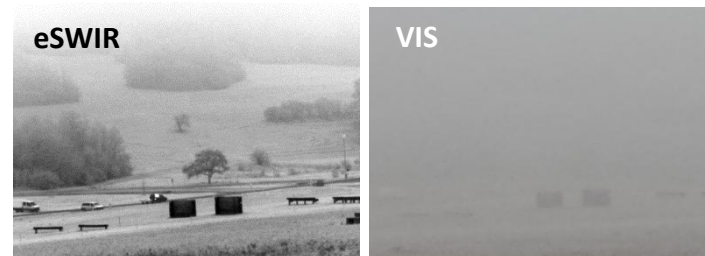
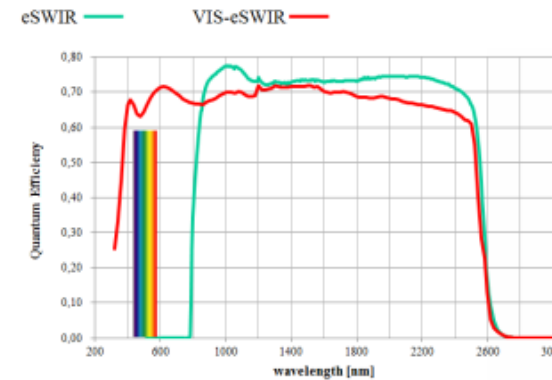
LPE MCT on CdTe

0.9 μm - 2.5 μm (eSWIR)

VIS Option 0.4 μm – 2.5 μm

Top 150K-175K, cooled by stirling cooler

- Hyperspectral imaging
- Low light level imaging
- Active imaging by laser illumination



- ❑ **1024 x 256 / 24x32 μm^2 pixel pitch**
 - Snapshot, ITR and IWR
 - Framerate up to 250 Hz
- ❑ **384 x 288 / 24x24 μm^2 pixel pitch**
 - Snapshot, ITR and IWR
 - Framerate up to 450 Hz
- ❑ **640 x 512 / 15x15 μm^2 pixel pitch**
 - Snapshot: ITR and IWR; Rolling Shutter
 - Framerate up to 120 Hz
- ❑ **640 x 512 / 10x10 μm^2 pixel pitch**
 - Snapshot: ITR and IWR; Rolling Shutter
 - Framerate up to 100 Hz



A close-up photograph of a microchip assembly process. A small, square, black microchip is mounted on a circular gold-colored substrate. This substrate is being held by a pair of gold-colored tweezers. Below the tweezers, a cylindrical metal component with a flange and a central hole is visible. The background is a blue surface with some mechanical parts.

**Thank you for your attention !
Questions ?**

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END

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